

CMLD2004G
SURFACE MOUNT SILICON
DUAL, ISOLATED
HIGH VOLTAGE
SWITCHING DIODE

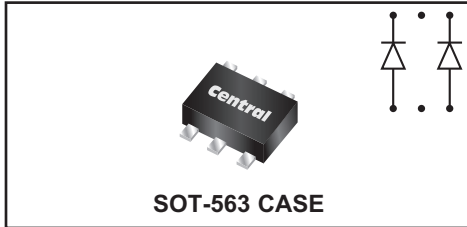


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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMLD2004G contains two (2) isolated high voltage silicon switching diodes, manufactured by the epitaxial planar process, epoxy molded in an SOT-563 surface mount package. These devices are designed for applications requiring high voltage capability.

MARKING CODE: DG



MAXIMUM RATINGS: ($T_A=25^\circ\text{C}$)

Continuous Reverse Voltage
 Peak Repetitive Reverse Voltage
 Peak Repetitive Reverse Current
 Continuous Forward Current
 Peak Repetitive Forward Current
 Peak Forward Surge Current, $t_p=1.0\mu\text{s}$
 Peak Forward Surge Current, $t_p=1.0\text{s}$
 Power Dissipation
 Operating and Storage Junction Temperature
 Thermal Resistance

SYMBOL

V_R 240
 V_{RRM} 300
 I_O 200
 I_F 225
 I_{FRM} 625
 I_{FSM} 4.0
 I_{FSM} 1.0
 P_D 250
 T_J, T_{stg} -65 to +150
 Θ_{JA} 500

UNITS

V
 V
 mA
 mA
 mA
 A
 A
 mW
 $^\circ\text{C}$
 $^\circ\text{C/W}$

ELECTRICAL CHARACTERISTICS PER DIODE: ($T_A=25^\circ\text{C}$ unless otherwise noted)

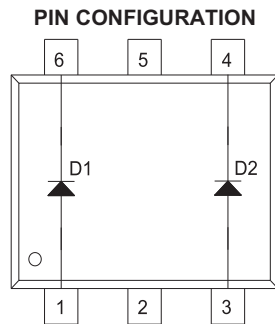
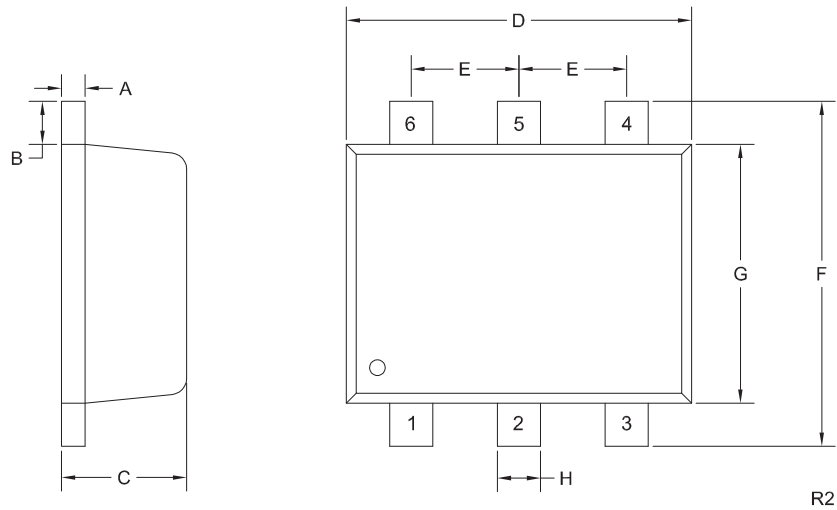
SYMBOL	TEST CONDITIONS	MIN	MAX	UNITS
I_R	$V_R=240\text{V}$		100	nA
I_R	$V_R=240\text{V}, T_A=150^\circ\text{C}$		100	μA
BV_R	$I_R=100\mu\text{A}$	300		V
V_F	$I_F=100\text{mA}$		1.0	V
C_J	$V_R=0, f=1.0\text{MHz}$		5.0	pF
t_{rr}	$I_F=I_R=30\text{mA}, I_{rr}=3.0\text{mA}, R_L=100\Omega$		50	ns

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SOT-563 CASE - MECHANICAL OUTLINE



LEAD CODE:

- 1) Anode D1
- 2) NC
- 3) Anode D2
- 4) Cathode D2
- 5) NC
- 6) Cathode D1

MARKING CODE: DG

SYMBOL	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.0027	0.007	0.07	0.18
B	0.008		0.20	
C	0.017	0.024	0.45	0.60
D	0.059	0.067	1.50	1.70
E	0.020		0.50	
F	0.059	0.067	1.50	1.70
G	0.043	0.051	1.10	1.30
H	0.006	0.012	0.15	0.30

SOT-563 (REV: R2)

R2 (15-June 2015)

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SERVICES

- Bonded Inventory
- Custom Electrical Screening
- Custom Electrical Characteristic Curves
- SPICE Models
- Custom Packaging
- Package Base Options
- Custom Device Development/ Multi Discrete Modules (MDM™)
- Bare Die Available for Hybrid Applications

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R2 (15-June 2015)